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coupled to said fastening member, wherein said heat sink is adapted to transfer heat from said interior portion to the external environment.

1742. (once amended) The electronic device as recited in claim 13, said face plate adapted to selectively control said electronics.

(once amended) A water-resistant electronic device comprising:

a housing having an interior portion, said housing is adapted to prevent water from entering said interior portion;

electronics mounted within said interior portion;

a face plate coupled to said housing; and

a heat sink, said heat sink adapted to be coupled to said housing, wherein said heat sink is adapted to transfer heat from said interior portion to the external environment, wherein said face plate has an opening formed therein and a door that is coupled to said face plate and is adapted to cover said opening in a sealed manner.

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1921. (once amended) A water-resistant electronic device comprising:

a housing having first and second sections, said first and second sections are adapted to be sealed together to form an interior portion, said interior portion is adapted to prevent water from entering therein;

an electronic component, said electronic component is adapted to be mounted in said interior portion

a fastening mechanism; and

a heat sink comprising a protuberance that extends into said housing and is coupled to said fastening mechanism, said heat sink adapted to be coupled to said housing by said fastening



mechanism, said heat sink adapted to be coupled with said electronic component, wherein said heat sink is adapted to transfer the heat that is generated by the electronic device to an external environment.

M34. (once amended) The electronic device as recited in claim 24, wherein said fastening mechanism includes a screw and a clip.

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33 (once amended) The electronic device as recited in claim 33, wherein said face plate is adapted to selectively control the electronic device.

35. (once amended) A water-resistant electronic device comprising:

a housing having first and second sections, said first and second sections are adapted to be sealed together to form an interior portion, said interior portion is adapted to prevent water from entering therein;

an electronic component, said electronic component is adapted to be mounted in said interior portion;

a face plate coupled to said housing; and

a heat sink, said heat sink adapted to be coupled to said housing and is adapted to be coupled with said electronic component, wherein said heat sink is adapted to transfer the heat that is generated by the electronic device to an external environment, wherein said face plate includes an opening and a hinged door for covering said opening in a sealed manner.



35 36. (once amended) A method for forming a water-resistant enclosure for an electronic device, said device includes a housing, an electronic component and a heat sink coupled to said housing by a fastening member, said heat sink including a protuberance that is in contact with said fastening member, wherein said housing is adapted to seal said electronic component within said housing, wherein said heat sink is adapted to be coupled within said housing and allow for





the transfer of heat generated by said electronic component within said housing to the external environment, the method comprising the steps of:

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mounting said electronic component in the housing;

sealing the housing in such a way to prevent water from entering the housing; and coupling the heat sink to said electronic component.

## PLEASE ADD THE FOLLOWING NEW CLAIMS

4551. (new) A water-resistant electronic device comprising:

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a housing having an interior portion, said housing is adapted to prevent water from entering said interior portion;

electronics mounted within said interior portion;

a heat sink, said heat sink adapted to be coupled to an exterior of said housing, wherein said heat sink is adapted to transfer heat from said interior portion to the external environment; and

a gasket positioned between said heat sink and said housing, said gasket providing a water-tight seal between said heat sink and said interior portion of said housing.

in a rim of an aperture formed in said housing, said heat sink being inserted into said aperture.

into an aperture formed in said housing.

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54. (new) The electronic device as recited in claim 54, wherein said heat sink includes a protuberance that extends into said interior portion of said housing to transfer heat from said electronics.

55. (new) The electronic device as recited in claim 51, further comprising a screw and a clip that secures said heat sink to said housing.

(new) The electronic device as recited in claim 1, wherein said housing includes separate top and bottom pieces, wherein said top and bottom pieces are sealed to one another to prevent water from entering the interior portion of said housing.

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57. (new) The electronic device as recited in claim 56, further comprising a gasket that seals said top and bottom pieces together to prevent water from entering said interior portion of said housing.

558. (new) An enclosure for electronic components comprising:

a housing comprising an interior portion and an opening formed in said housing into said interior portion, said housing being adapted to prevent water from entering said interior portion;

a door attached to said housing, said door sealably covering said opening and being moveable between open and closed positions; and

a heat sink sealably coupled to an exterior of said housing, wherein said heat sink transfers heat from said interior portion to the external environment.

(new) The enclosure as recited in claim 58, wherein said door is hinged to said housing and, when closed, forms a snug engagement with said housing about said opening.

(new) The enclosure as recited in claim 59, further comprising a door gasket provided between and forming a compression seal with said door and said housing.



